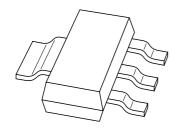
### **DISCRETE SEMICONDUCTORS**

# DATA SHEET



## BSP60; BSP61; BSP62 PNP Darlington transistors

Product data sheet Supersedes data of 1999 Apr 29 2001 May 31



### **PNP Darlington transistors**

**BSP60**; **BSP61**; **BSP62** 

#### **FEATURES**

- High current (max. 0.5 A)
- Low voltage (max. 80 V)
- Integrated diode and resistor.

#### **APPLICATIONS**

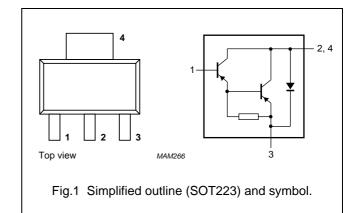
- Industrial switching applications such as:
  - Print hammer
  - Solenoid
  - Relay and lamp drivers.

#### **DESCRIPTION**

PNP Darlington transistor in a SOT223 plastic package. NPN complements: BSP50, BSP51 and BSP52.

#### **PINNING**

PIN	DESCRIPTION	
1	base	
2, 4	collector	
3	emitter	



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter			
	BSP60		_	-60	V
	BSP61		_	-80	V
	BSP62		_	-90	V
V <sub>CES</sub>	collector-emitter voltage	$V_{BE} = 0$			
	BSP60		_	-45	V
	BSP61		_	-60	V
	BSP62		_	-80	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-5	V
I <sub>C</sub>	collector current (DC)		_	-1	А
I <sub>CM</sub>	peak collector current		_	-2	Α
I <sub>B</sub>	base current (DC)		_	-100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	1.25	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>.
 For other mounting conditions, see "Thermal considerations for the SOT223 in the General Part of associated Handbook".

2001 May 31 2

### PNP Darlington transistors

BSP60; BSP61; BSP62

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	98	K/W
R <sub>th j-s</sub>	thermal resistance from junction to solder point		17	K/W

#### Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>. For other mounting conditions, see *"Thermal considerations for the SOT223 in the General Part of associated Handbook"*.

#### **CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CES</sub>	collector cut-off current					
	BSP60	$V_{BE} = 0; V_{CE} = -45 \text{ V}$	_	_	-50	nA
	BSP61	$V_{BE} = 0; V_{CE} = -60 \text{ V}$	_	_	-50	nA
	BSP62	$V_{BE} = 0; V_{CE} = -80 \text{ V}$	_	_	-50	nA
I <sub>EBO</sub>	emitter cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = -4 V	-	_	-50	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = -10 \text{ V}$ ; note 1; see Fig.2				
		$I_{\rm C} = -150 \; {\rm mA}$	1000	_	_	
		$I_{\rm C} = -500 \; {\rm mA}$	2000	_	_	
V <sub>CEsat</sub>	collector-emitter saturation	$I_C = -500 \text{ mA}; I_B = -0.5 \text{ mA}$	-	_	-1.3	V
voltage		$I_C = -500 \text{ mA}; I_B = -0.5 \text{ mA};$ $T_j = 150 \text{ °C}$	_	_	-1.3	V
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_C = -500 \text{ mA}; I_B = -0.5 \text{ mA}$	-	_	-1.9	V
f <sub>T</sub>	transition frequency	$I_C = -500 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 100 MHz	_	200	_	MHz
Switching times (between 10% and 90% levels); see Fig.3						
t <sub>on</sub>	turn-on time	$I_{Con} = -500 \text{ mA}; I_{Bon} = -0.5 \text{ mA};$	_	400	_	ns
t <sub>off</sub>	turn-off time	I <sub>Boff</sub> = 0.5 mA	_	1500	_	ns

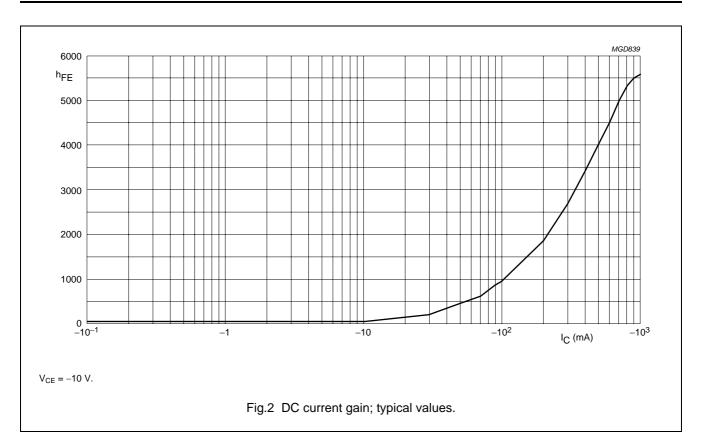
#### Note

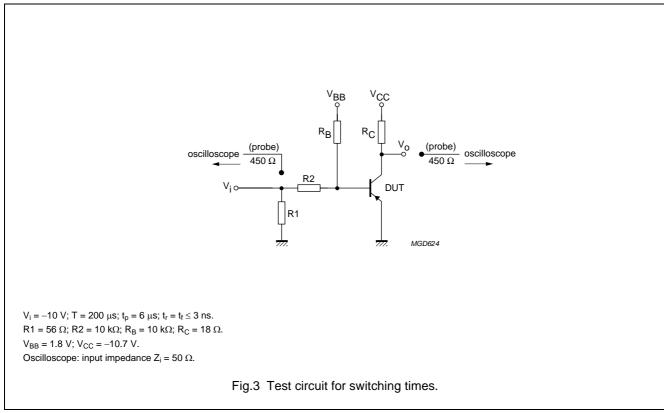
1. Pulse test:  $t_p \leq 300~\mu s;~\delta \leq 0.02.$ 

2001 May 31 3

### PNP Darlington transistors

### BSP60; BSP61; BSP62





2001 May 31 4

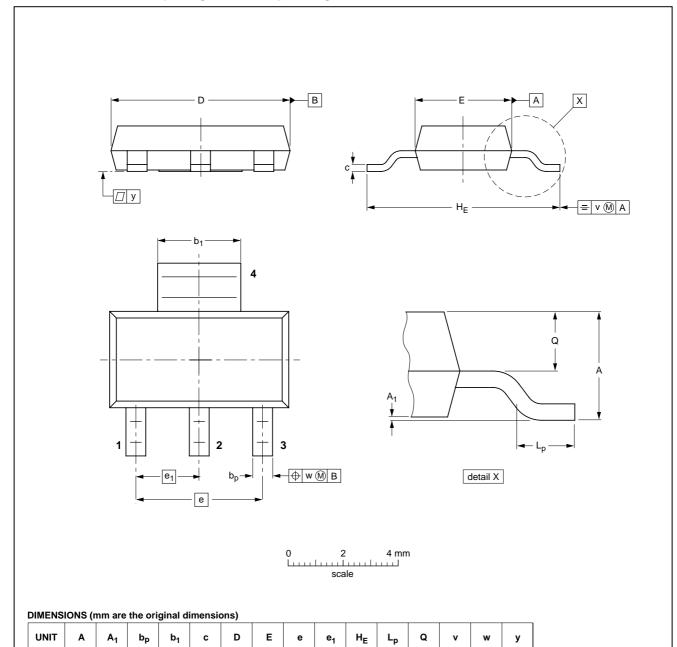
### PNP Darlington transistors

BSP60; BSP61; BSP62

#### **PACKAGE OUTLINE**

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

**SOT223** 



OUTLINE		REFERENCES			EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUL DATE
SOT223			SC-73			<del>-97-02-28</del> 99-09-13

7.3

1.1

0.95

0.85

0.1

0.1

2001 May 31 5

0.80

0.60

0.10

0.01

1.8

mm

3.1 2.9 6.7

3.7

3.3

0.32

0.22

### PNP Darlington transistors

BSP60; BSP61; BSP62

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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6

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